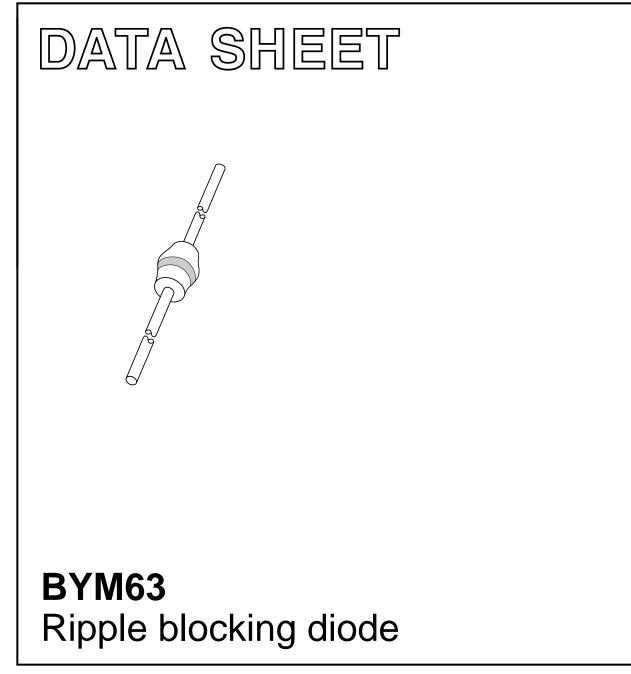
DISCRETE SEMICONDUCTORS



Product specification Supersedes data of December 1995 File under Discrete Semiconductors, SC01 1996 Jun 10



# BYM63

#### FEATURES

- Glass passivated
- High maximum operating temperature
- Low leakage current
- Excellent stability
- Guaranteed minimum turn-on time for absorbing forward current transients and oscillations
- Specially designed as rectifier in the auxiliary power supply in e.g. switched mode power supplies
- Available in ammo-pack.
- Also available with preformed leads for easy insertion.

### LIMITING VALUES

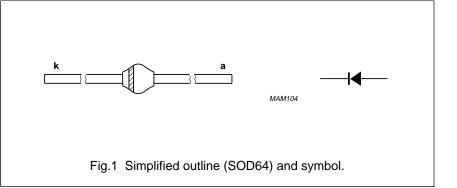
In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>RRM</sub>	repetitive peak reverse voltage		_	300	V
V <sub>R</sub>	continuous reverse voltage		_	300	V
I <sub>F(AV)</sub>	average forward current	averaged over any 20 ms period; $T_{tp} = 55 \text{ °C}$ ; lead length = 10 mm; see Fig.2; see also Fig.4	-	2.4	A
		averaged over any 20 ms period; T <sub>amb</sub> = 65 °C; PCB mounting (Fig.8); see Fig.3; see also Fig.4	_	1.0	A
I <sub>FRM</sub>	repetitive peak forward current	T <sub>tp</sub> = 55 °C	-	21	А
		T <sub>amb</sub> = 65 °C	_	8.5	А
I <sub>FSM</sub>	non-repetitive peak forward current	t = 10 ms half sine wave; $T_j = T_{j max}$ prior to surge; $V_R = V_{RRMmax}$	_	45	A
T <sub>stg</sub>	storage temperature		-65	+175	°C
T <sub>i</sub>	junction temperature		-65	+175	°C

#### DESCRIPTION

Rugged glass SOD64 package, using a high temperature alloyed construction.

This package is hermetically sealed and fatigue free as coefficients of expansion of all used parts are matched.



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### **ELECTRICAL CHARACTERISTICS**

 $T_i = 25 \ ^{\circ}C$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V <sub>F</sub>	forward voltage	$I_F = 2 A; T_j = T_{j max}; see Fig.5$	_	_	1.34	V
		I <sub>F</sub> = 2 A; see Fig.5	_	_	2.30	V
I <sub>R</sub>	reverse current	V <sub>R</sub> = V <sub>RRMmax</sub> ; see Fig.6	_	-	10	μA
		V <sub>R</sub> = V <sub>RRMmax</sub> ; T <sub>j</sub> = 165 °C; see Fig.6	-	-	150	μA
t <sub>fr</sub>	forward recovery time	when switched to I <sub>F</sub> = 5 A in 50 ns; see Fig.9	-	-	1.5	μs
t <sub>on</sub>	turn-on time	when switched from $V_F = 0 V$ to $V_F = 3 V$ ; measured between 10% and 90% of $I_{F max}$ ; see Fig.11	400	_	_	ns
t <sub>rr</sub>	reverse recovery time	when switched from $I_F = 0.5$ A to $I_R = 1$ A; measured at $I_R = 0.25$ A; see Fig.11	_	_	150	ns
C <sub>d</sub>	diode capacitance	$f = 1 \text{ MHz}; V_R = 0 \text{ V}; \text{ see Fig.7}$	_	65	_	pF

#### THERMAL CHARACTERISTICS

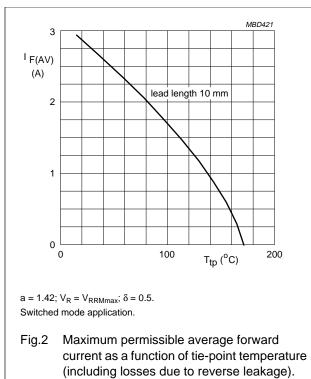
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th j-tp</sub>	thermal resistance from junction to tie-point	lead length = 10 mm	25	K/W
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	75	K/W

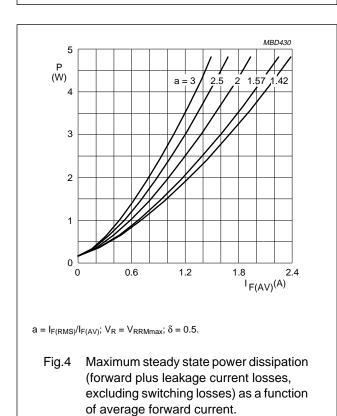
#### Note

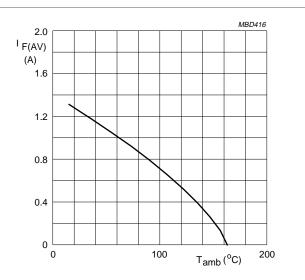
1. Device mounted on an epoxy-glass printed-circuit board, 1.5 mm thick; thickness of Cu-layer ≥40 μm, see Fig.8. For more information please refer to the *'General Part of Handbook SC01.'* 

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### **GRAPHICAL DATA**

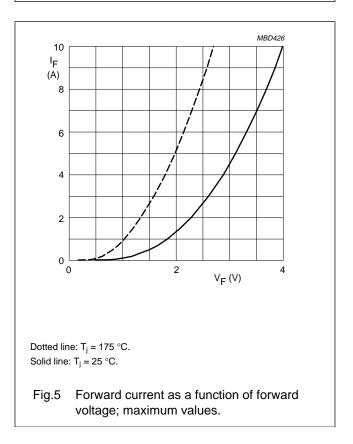




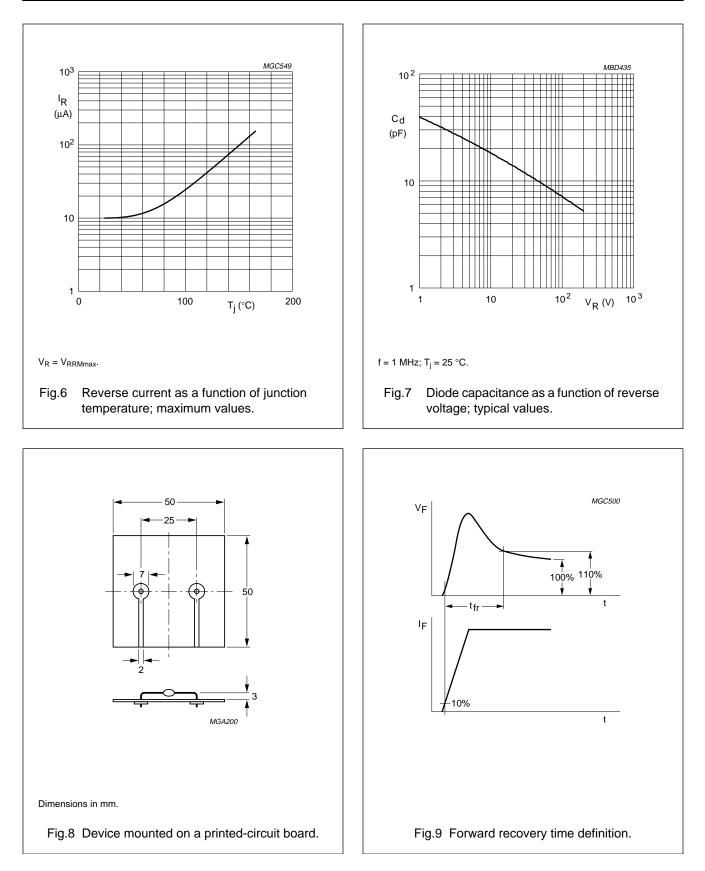


 $\label{eq:rescaled} \begin{aligned} &a=1.42; \ V_R=V_{RRMmax}; \ \delta=0.5. \\ & \text{Device mounted as shown in Fig.8.} \\ & \text{Switched mode application.} \end{aligned}$ 

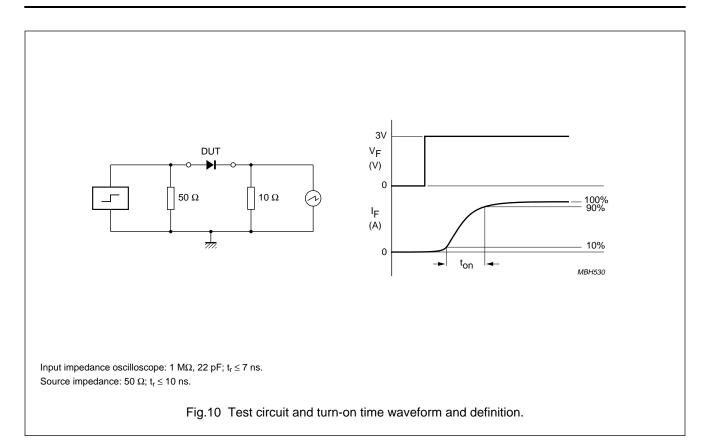
Fig.3 Maximum permissible average forward current as a function of ambient temperature (including losses due to reverse leakage).

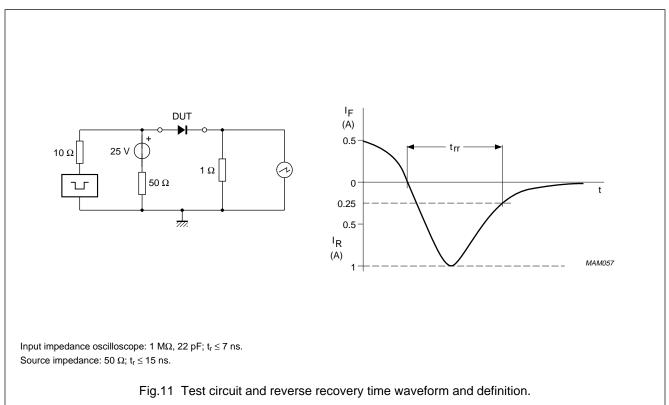


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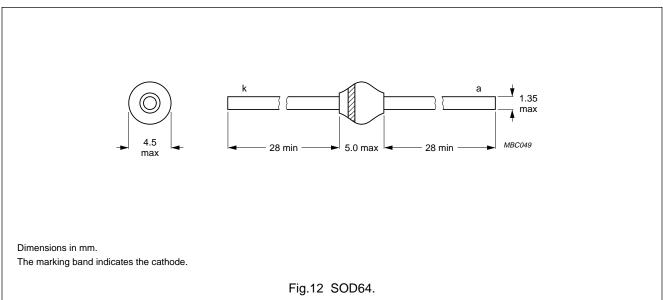






### BYM63

#### PACKAGE OUTLINE



#### DEFINITIONS

Data Sheet Status		
Objective specification	specification This data sheet contains target or goal specifications for product development.	
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.	
Product specification	This data sheet contains final product specifications.	
Limiting values		
more of the limiting values m of the device at these or at a	accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or ay cause permanent damage to the device. These are stress ratings only and operation my other conditions above those given in the Characteristics sections of the specification niting values for extended periods may affect device reliability.	
Application information		
Where application information	n is given, it is advisory and does not form part of the specification.	

#### LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.